DKS-SolderPaste15G-ND

Solder Paste No-Clean Sn63/Pb37 in 5cc Syringe 15g T3 Mesh

Product highlights:

- Printing speeds up to 100 mm/sec
- Long stencil life
- Wide process window
- Clear residue
- Low voiding
- Excellent wetting compatibility on most board finishes
- Dispense grade
- Compatible with enclosed print heads
- Passed BONO test

Specifications:

Alloy:	SN63/Pb37
Mesh Size:	T3
Micron Range:	25 - 45
Flux Type:	Synthetic No-Clean
Flux Classification:	REL0
Metal Load:	88% Metal by Weight
Melting Point:	183°C (361°F)
Packaging:	5cc/15g syringe
Shelf Life:	Refrigerated >12 months, Unrefrigerated >6 months *See notes below:

Shelf life notes:

Our solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Our solder paste is manufactured using high quality synthetic flux and precision atomized metal powder.

Printer operation

Print Speed: 25-100mm/sec
Squeegee Pressure: 70-250g/cm of blade
Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
>4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA)

Storage and handling

Do not freeze. Refrigerate at 3-8°C (37-46°F). Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

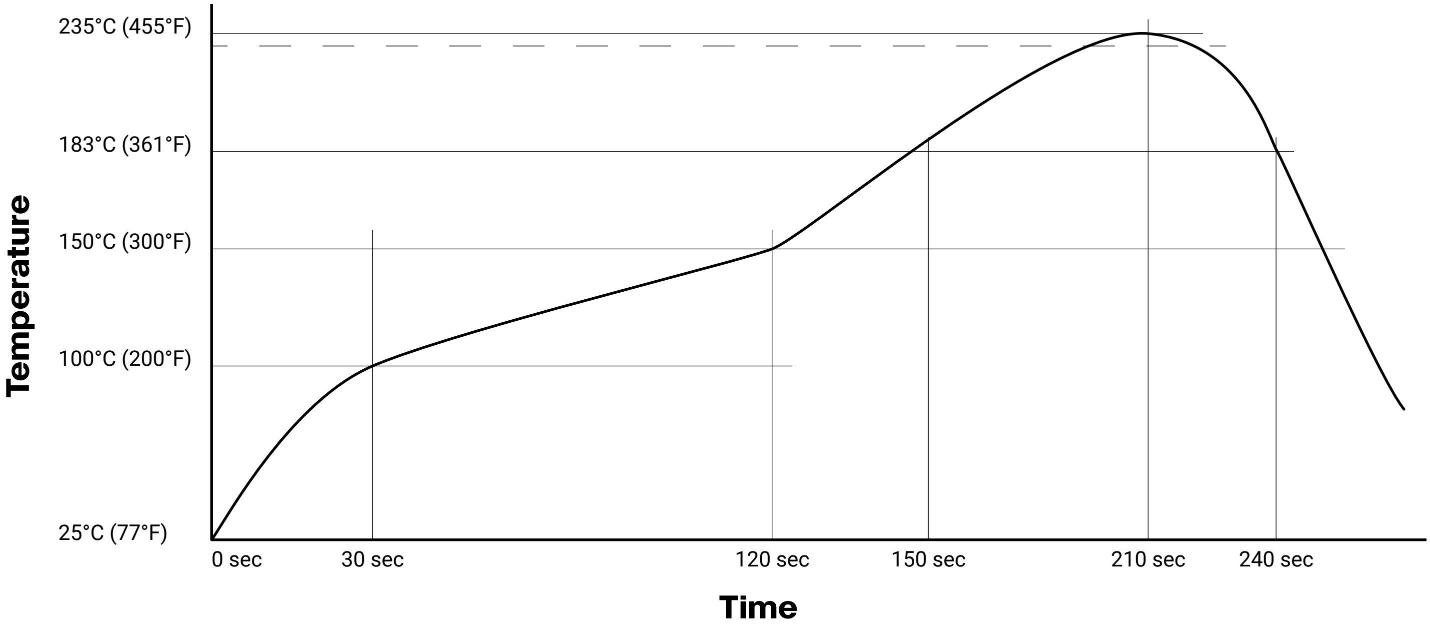
This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following industry standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	No

Recommended profile

Reflow profile for Sn63/Pb37 solder assembly, designed as a starting point for process optimization.



Test results

Test J-STD-004 or other requirements as stated	Test requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	>100MΩ (No-Clean)
Track Value	IPC-TM-650: 2.4.44	44g
Viscosity - Malcom @ 10RPM/25°C (x10³mPa/s)	IPC-TM-650: 2.4.34.4	Print: 210-300, Dispense: 100-140
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present